



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: )  
Shriram Ramanathan et al. )  
Serial No.: 10/611,395 )  
Filed: June 30, 2003 )  
For: Methods for Bonding Wafers )  
Using a Metal Interlayer )  
Examiner: Heather Anne Doty )  
Group Art Unit: 2813 )  
Attorney Docket No.: 42P16666 )

---

Mail Stop RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Sir:

This Preliminary Amendment accompanies a Request for Continued Examination (RCE) filed in accordance with 37 C.F.R. § 1.114.

**INTRODUCTORY COMMENTS**

The following amendments and remarks are proposed in response to the Final Office Action mailed September 28, 2005.

Claims 1-42 were pending in the application, but claims 28-42 have been withdrawn from further consideration. Claims 1-11 and 13-26 have been rejected, and claims 12 and 27 stand objected to. Applicants propose herein to amend each of claims 1 and 13. Applicants also propose to cancel withdrawn claims 28-42.

Applicants respectfully request reconsideration of the application in view of the amendments set forth herein and the accompanying remarks.